

**/ Descriptions**

P

**/ Features**

±

。 HF Product.

**/ Applications**

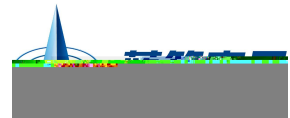
**/ Equivalent Circuit**

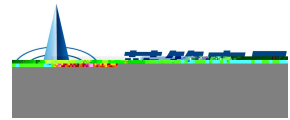


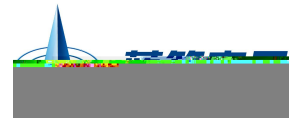
**/ Pinning**

**/ Marking**

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/ Electrical Characteristic Curve

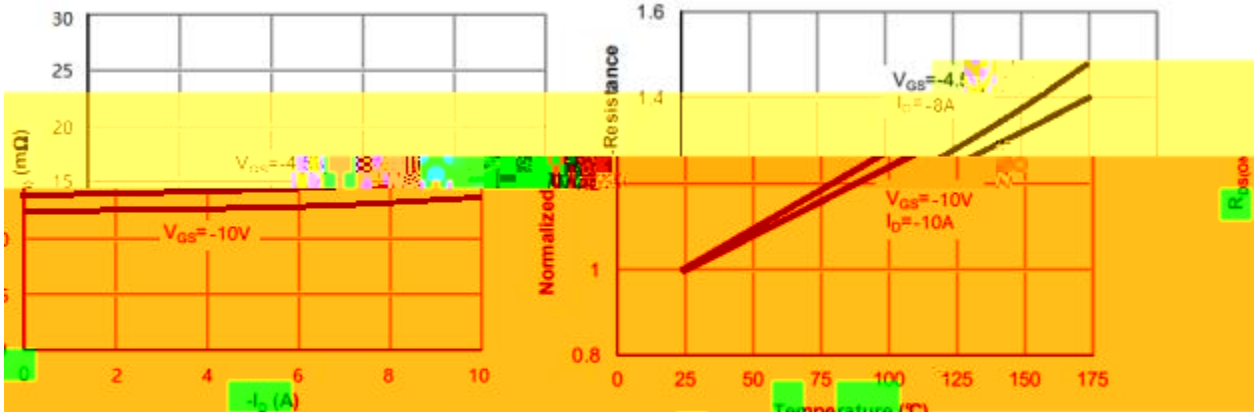
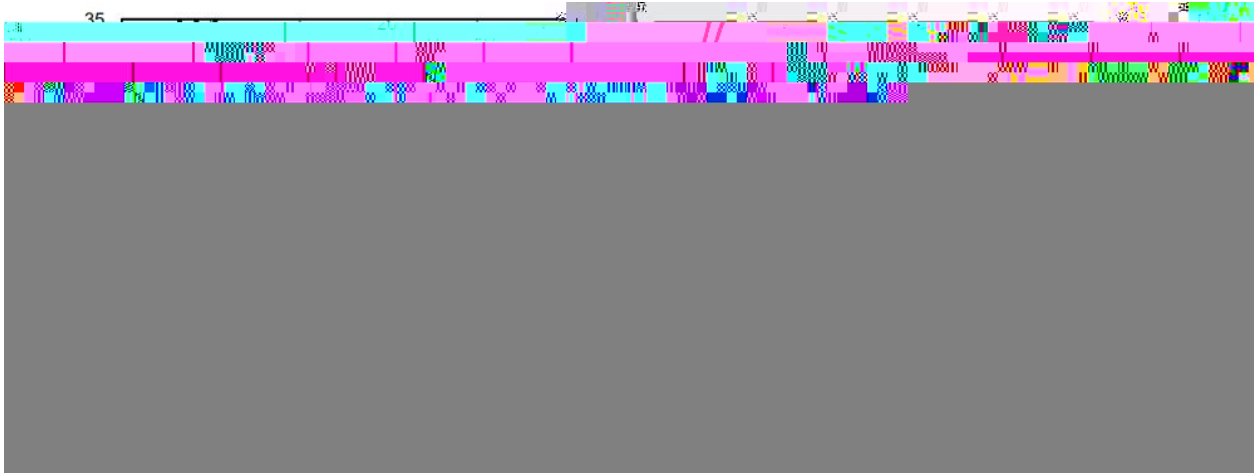
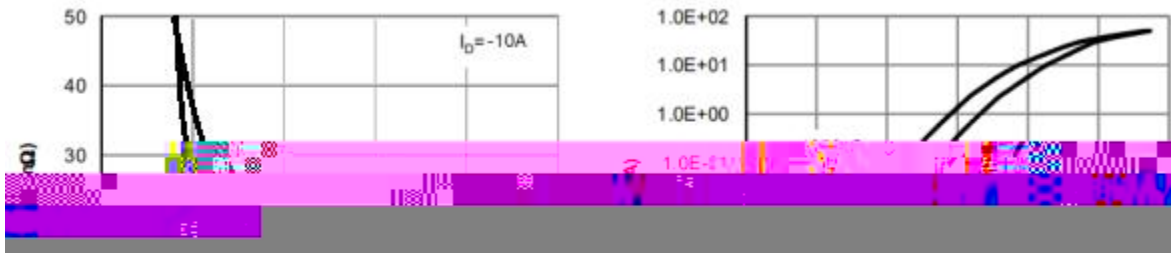
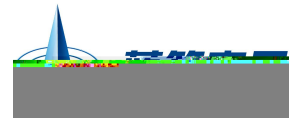


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

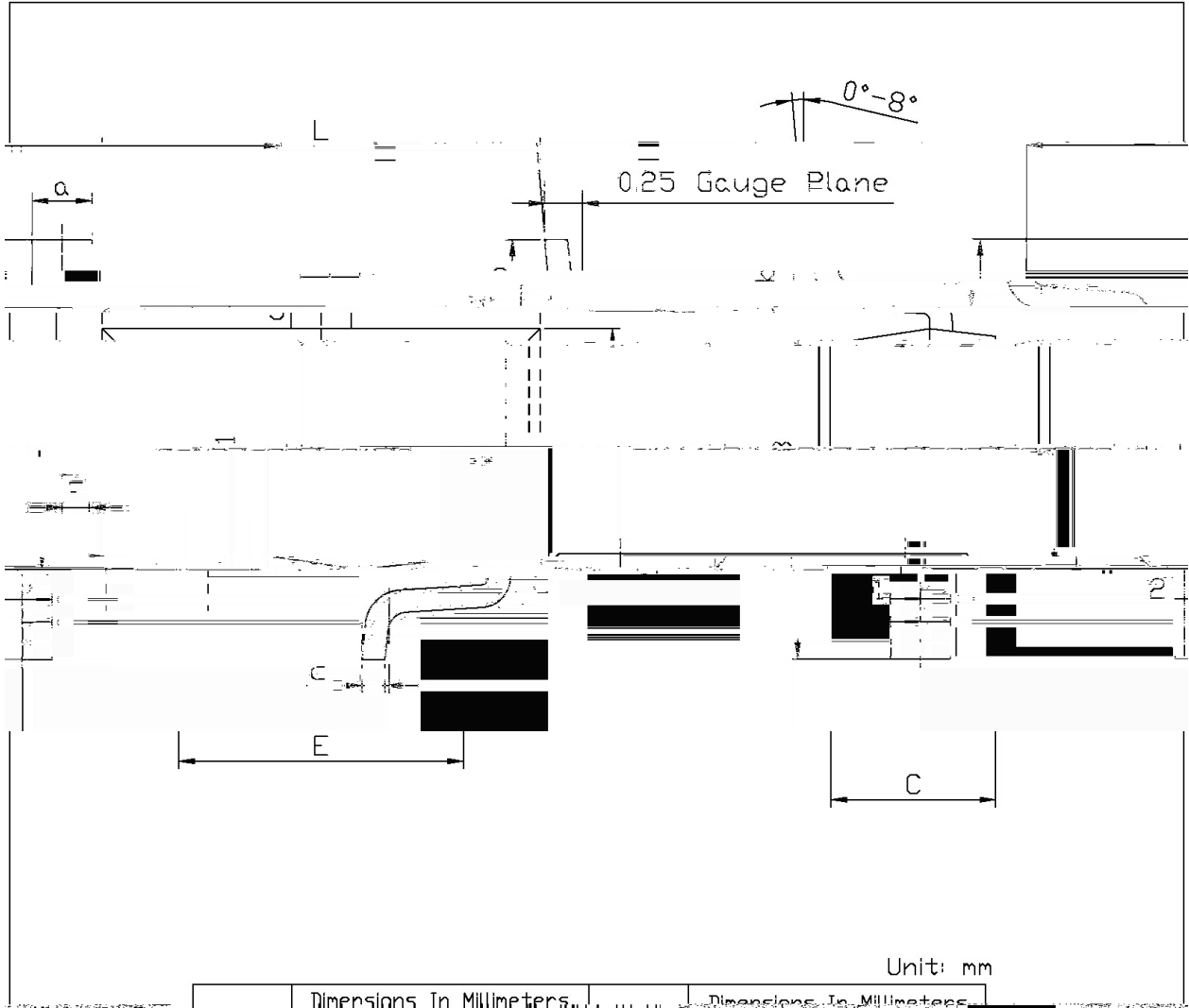
Figure 4: On-Resistance vs. Temperature



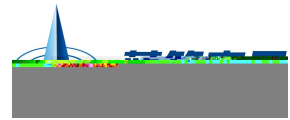




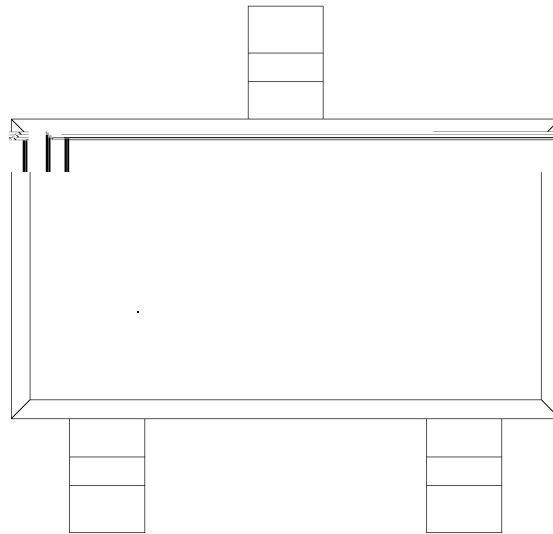
/ Package Dimensions

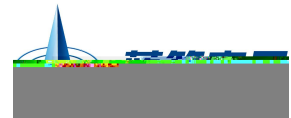


Dimensions In Millimeters		Dimensions In Millimeters	
2.82	3.02	a	0.35
0.50			

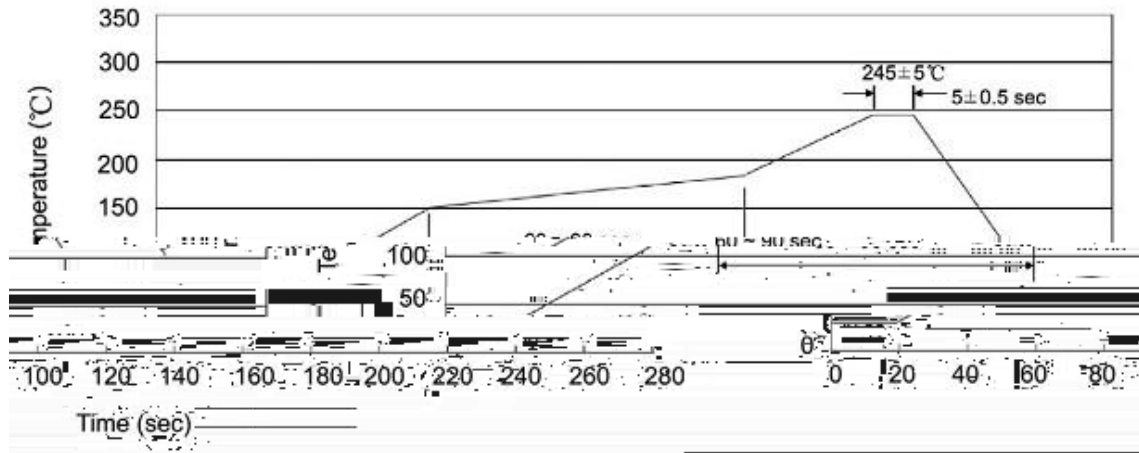


/ Marking Instructions





**( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



± ± ± ±

**/ Resistance to Soldering Heat Test Conditions**

± ± ± ±

**/ Packaging SPEC.**

封装形式	包装数量					包装尺寸		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT23-3	3000	10	30000	4	120000	7" ×8	210×205×205	445×230×435

**/ Notices**